

L Number	Hits	Search Text	DB	Time stamp
1	14	(phenolsulfonic near2 acid) and (cmp or chemical near2 mechanical near2 (planar\$8 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:21
2	2705	(molybdenum) and (cmp or chemical near2 mechanical near2 (planar\$8 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:21
3	16	(molybdenum near10 salt) and (cmp or chemical near2 mechanical near2 (planar\$8 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:27
4	33	copper near2 sulfate same slurry and (chemical near2 mechanical near2 (planariz\$5 or polish\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:29
5	470404	copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:33
6	1765	(copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:35
7	763	(copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) near10 slurr\$6 same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:35
8	18	(copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) near10 slurr\$6 near5 additiv\$6 same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 14:37
9	16	(copper near2 sulfate or "cuso.sub.4" or edta or "feno.sub.3" ferric near2 nitrate or iron near2 nitrate or koh or potassium near2 hydroxide or "k.sub.2s.ub.2o.sub.8" or naoh or sodium near2 hydroxide or sodium near2 nitride or ammonium near2 hydroxide) near10 slurr\$6 same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7)) same copper near2 layer (cucl or copper near2 chloride or iron near2 chloride or ferric near2 chloride or fecl or "fecl.sub.3") near10 slurr\$6 same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7)) same copper near2 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 15:54
10	0		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 15:54

11	3	(cucl or copper near2 chloride or iron near2 chloride or ferric near2 chloride or fecl or "fecl.sub.3") same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7)) same copper near2 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/15 15:55
12	44	(cucl or copper near2 chloride or iron near2 chloride or ferric near2 chloride or fecl or "fecl.sub.3") same (cmp or chemical near2 mechanical near2 (planar\$7 or polish\$7)) same copper near2 layer 6582512.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/15 16:36
13	2		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/15 16:36
-	135	single near2 step near5 slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 11:52
-	11	single near2 step near5 slurry and (copper near2 tantalum or cu\$1ta)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 12:00
-	17	single near2 step near5 slurry and (copper same tantalum or cu\$1ta)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 13:35
-	79	single near5 slurry and (copper same tantalum or cu\$1ta)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 13:35
-	83	single near5 slurry and (copper same (tantalum or cu\$1ta or tan or ta))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 13:35
-	55	single near5 slurry and (copper same (tantalum or cu\$1ta or tan or ta)) and (peroxide or sulfuric or ntric or acetic or phosphoric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 13:37
-	86	single near5 slurry same (peroxide or sulfuric or ntric or acetic or phosphoric or "h.sub.2o.sub.2" or "h.sub.3po.sub.4" or "h.sub.2so.sub.4" or "hno.sub.3")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 13:38
-	17	single near5 slurry same (peroxide or sulfuric or ntric or acetic or phosphoric or "h.sub.2o.sub.2" or "h.sub.3po.sub.4" or "h.sub.2so.sub.4" or "hno.sub.3") and ((cu copper) same (tantalum or ta or tan))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 13:43
-	2	6063306.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:01
-	2	20020020833.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:13
-	841	(copper or cu) near10 (tantalum or ta or tan) same planar\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:14

	172	(copper or cu) near10 (tantalum or ta or tan) near10 planar\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:48
	16	((copper or cu) near10 (tantalum or ta or tan) near10 planar\$8) and (single near2 step) same (slurry or solution)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:24
	2	5447887.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:24
	48	(copper or cu) near10 (tantalum or ta or tan) near10 planar\$8 same select\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:49
	38	(copper or cu) near10 (tantalum or ta or tan) near10 planar\$8 same selectiv\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 14:59
	123	(copper or cu) near10 (tantalum or ta or tan) and (single or one near2 step) near10 slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 15:05
	2	5954997.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 10:43
	6	(cmp or chemical adj mechanical adj planar\$) and abrasive near2 particle near10 coating near10 ("ceo.sub.2" or cerium near2 oxide or ceo2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 10:46
	2	5697992.pn. and abrasive near2 particle near10 ("ceo.sub.2" or cerium near2 oxide or ceo2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 10:50
	14	abrasive near2 particle near10 ("ceo.sub.2" or cerium near2 oxide or ceo2) near10 (coat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:02
	8	abrasive near2 particle same sol near2 method and cmp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 10:58
	5	("4588576" "5004711" "5238625").pn. and sol	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 10:56
	39	abrasive near2 particle same sol and cmp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 10:58
	421	abrasive near2 particle near10 ("ceo.sub.2" or cerium near2 oxide or ceo2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:02

	17	abrasive near2 particle near10 ("ceo.sub.2" or cerium near2 oxide or ceo2) near10 (coat\$5 or cover\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:09
	2703	abrasive near2 particle near10 (coat\$5 or cover\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:11
	2635	abrasive near2 particle near10 (coat\$5 or cover\$5) near2 particle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:13
	8	abrasive near2 particle near10 (coat\$5 or cover\$5) near2 particle near10 ("sio.sub.2" or "alo.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:11
	202	(abrasive near2 particle near10 (coat\$5 or cover\$5) near2 particle) and cmp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:12
	11	((abrasive near2 particle near10 (coat\$5 or cover\$5) near2 particle) and cmp) and @py<1999	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:12
	2365	abrasive near2 particle near10 (coat\$5) near2 particle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:13
	141	(abrasive near2 particle near10 (coat\$5) near2 particle) and cmp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:13
	10	((abrasive near2 particle near10 (coat\$5) near2 particle) and cmp) and @py<2000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:58
	1139	(cu near2 (ta or tan) or copper near4 tantalum) same (polish\$5 or planar\$7 or cmp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 11:59
	1	(cu near2 (ta or tan) or copper near4 tantalum) same (polish\$5 or planar\$7 or cmp) and slurry same (fecl cucl "fecl.sub.3" or iron near2 chloride or copper near2 chloride)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 12:00
	4383	slurry same metal near2 salt	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:25
	16422	(copper or cu) near10 (cmp or polish\$5 or planar\$8) slurry same metal near2 salt	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:26
	79	(copper or cu) near10 (cmp or polish\$5 or planar\$8) and slurry same metal near2 salt	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:26

	5	(copper or cu) near10 (cmp or polish\$5 or planar\$8) and slurry same ("fecl" or "fecl.sub.3" or "cucl.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:28
	291	slurry same ("fecl" or "fecl.sub.3" or "cucl.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:28
	54	slurry same ("fecl" or "fecl.sub.3" or "cucl.sub.2") same (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:29
	8	slurry same ("fecl" or "fecl.sub.3" or "cucl.sub.2") same (polish\$5 or planar\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:29
	21	slurry same ("fecl" or "fecl.sub.3" or "cucl.sub.2") same (additiv\$5 or stabiliz\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:30
	17	slurry same ("fecl" or "fecl.sub.3" or "cucl.sub.2") and (cmp or chemical near2 mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:32
	24	slurry same (ferric near2 chloride) and (cmp or chemical near2 mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:43
	31	slurry same (copper near2 sulfate or "cuso.sub.4") and (cmp or chemical near2 mechanical) near10 (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:50
	104	slurry same (koh) and (cmp or chemical near2 mechanical) near10 (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:54
	0	(molybdenum near2 salt or phenolsulfonic near2 acid) same slurry and (cmp or chemical near2 mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:55
	31	(phenolsulfonic near2 acid) and (cmp or chemical near2 mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:45
	43066	organic near2 acid near10 acetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:46
	18797	(organic near2 acid near10 acetic) and @py<1995	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:46
	25590	organic near2 acid near2 acetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:47

	228	organic near2 acid near2 acetic and cmp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:47
	13	(organic near2 acid near2 acetic and cmp) and @py<1998	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:48
	304	oxide near10 particle same sol near2 method	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:48
	211	oxide near10 particle near10 sol near2 method	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:48
	67	(oxide near10 particle near10 sol near2 method) and @py<1999	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:49
	19	sol same solgel near10 method	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:50
	7824	sol near2 method	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:50
	30	sol near2 method same abrasive near2 particle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:52
	298	sol adj method	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:53
	221	sol adj method and particle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:53
	109	sol adj method and particle near10 oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 14:54
	20	sol adj method and particle and (cmp or chemical near2 mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 15:39
	57	(fan near2 zhang or joseph near2 levert or daniel near2 towery).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 15:39
	17	((fan near2 zhang or joseph near2 levert or daniel near2 towery).in.) and (copper near10 tantalum or cu near2 ta)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:00

	10097	etching near10 planar\$9	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 15:53
	233	etching near10 planar\$9 same slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 15:53
	39	etching near10 planar\$9 same slurry and @py<1999	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 15:53
	2	4944836.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:09
	402	potassium near2 salt near10 koh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:09
	0	potassium near2 salt near10 koh and cmp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:09
	11	potassium near2 salt near10 koh same slurr\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:11
	13060	mol same slurr\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:11
	123	(mo molybdenum or phenolsulfonic) same slurr\$6 and (cmp or chemical near2 mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:12
	15	(mo molybdenum or phenolsulfonic) near10 slurr\$6 and (cmp or chemical near2 mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:13
	3	(mo molybdenum or phenolsulfonic) near10 slurr\$6 and (cmp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:13
	10297	(mo molybdenum or phenolsulfonic) and (cmp or chemical near2 mechanical near2 (polish\$5 or planar\$8))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:14
	1072	(mo molybdenum or phenolsulfonic) same (cmp or chemical near2 mechanical near2 (polish\$5 or planar\$8))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:14
	201	(mo molybdenum or phenolsulfonic) same (cmp or chemical near2 mechanical near2 (polish\$5 or planar\$8)) and @py<2000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:15

-	35	(molybdenum or phenolsulfonic) same (cmp or chemical near2 mechanical near2 (polish\$5 or planar\$8)) and @py<2000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:21
-	3001	phenolsulfonic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:21
-	2931	phenolsulfonic near2 acid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 16:21
-	12	(phenolsulfonic near2 acid) and (cmp or chemical near2 mechanical near2 planar\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/15 14:19